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Company Overview

Q3 2020 Segment Revenue Contribution

We are a leading global supplier of hardware and software solutions in the manufacturing of semiconductors and electronics

- **SMT Solutions**: 41.0%
- **Semiconductor Solutions**: 44.9%
- **Materials**: 14.1%

- #2 in SMT Equipment Market
- #3 in Leadframe Market
- #1 in Assembly and Packaging Equipment Market

- **1975**: Incorporated
- **1989**: Listed in Hong Kong Stock Exchange
- **USD4.2 bn**: Market Capitalisation
- **2018 Top 100 Global Technology Leaders**: Recognised by Thomson Reuters

1 As at 30 September 2020
2 VLSI, SMT and SEMI Market Intelligence
Geographical Presence

Sales Offices

- Hong Kong
- Beuningen
- Boston
- Porto
- Munich
- Regensburg
- Huizhou (Huizhou)
- Taoyuan
- Chengdu (Chengdu)
- Fuyong (Fuyong)
- Longgang (Longgang)
- Johor
- Shenzhen
- Singapore
- Longgang (龙岗)
- Weymouth
- Munich
- Beuningen

Business Centre / R&D / Manufacturing Site

- Patents on leading edge technologies
- R&D centres worldwide
- Manufacturing facilities

>2,000 Global R&D staff

>1,400 Patents on leading edge technologies

11 R&D centres worldwide

12 Manufacturing facilities
Core Capabilities

Comprehensive Suite of Packaging & Assembly and SMT Solutions
(A General Process Flow for IC and Discrete)

From Wafer...

Deposition and Plating

Testing & Packing

Wafer Backside Grinding

Wafer Mount & Singulation

Die Bonding and Epoxy Curing

Grooving

Saw or Laser

BGA, QFN and LGA Packages

Solder Ball Placement

Leaded Package

Marking

Plasma and Wire Bonding

Saw or Laser

Automated Optical Inspection

Testing & Packing

Molding & PMC

1st Level Packaging (SEMI Solutions)

2nd Level Packaging (SMT Solutions)

Solution offered by ASMPT

Legend

To End Device

Solder Paste Printing

Solder Paste Measurement

Component Placement

Post Placement

Trim & Form

Plating

From Wafer…

Plating

Deposition

Testing & Packing

Plating

From Wafer
Core Capabilities
Comprehensive Suite of Packaging and Assembly Solutions
(A General Process Flow for LED and CIS)

Conventional LED Packaging Solutions
- Laser Grooving
- Sub-Surface Dicing & Laser Scribing
- Map Sorting
- Die Bonding
- Wire Bonding
- Phosphor Layer Attach
- Inspection

CIS Packaging Solutions
- Dicing/Grooving
- Die Attach
- Snap Cure
- Wire Bonding
- Plasma Cleaning
- DI-Water Cleaning
- AOI Inspection
- Housing Attach
- Active Alignment

Legend
Solution offered by ASMPT
Core Capabilities
Comprehensive Suite of Advanced Packaging Solutions

Advanced Packaging Technology Enabler

End Applications

Heterogeneous Integration
System-in-Package
System-on-Chip

X-PU
Silicon Interposer

High Bandwidth Memory

FIREBIRD
TCB
FLI

NEXX
PVD | ECD
Bumping, TSV & RDL

Cloud Computing,
Datacentres for
High Performance Computing

Automotive Sensors,
LIDAR, Camera, Body
Electronics, Safety
Systems, Infotainment

Graphics Processing Unit
for VR/AR & AI

IoT: Wearables

Laser 1205
Laser Separation
Wafer Dicing and Grooving

SIPLACE CA
DIE ATTACH & SMT
Wafer and SMT Feeders

NUCLEUS
Pick and Place
Wafer and Panel

ORCAS
Encapsulation
Wafer and Panel

Laser Separation
Wafer Dicing and Grooving

Wafer Level Mold
Underfill
(Protects Integrated Wafer)

Wafer and Panel

Silicon Interposer

Laser Separation
Wafer Dicing and Grooving

Wafer and Panel
Core Capabilities

Widespread use of ASMPT Technology (Using Smartphone as an Example)

- CMOS Image Sensor (CIS)
- Die and Wire Bonder
- Advanced Packaging (AP)
- Light Emitting Diode (LED)
- Surface Mount Technology (SMT)
- System in Package (SiP)
End-Market Applications
Wide Diversity of Semiconductor Usage

<table>
<thead>
<tr>
<th>Mobility, Comm. and IT</th>
<th>Optoelectronics</th>
<th>Automotive</th>
<th>Power Management &amp; Energy</th>
<th>Industrial</th>
<th>Consumer</th>
</tr>
</thead>
<tbody>
<tr>
<td>Personal Computers</td>
<td>Virtual Reality</td>
<td>LIDAR Sensors</td>
<td>Electric Vehicles</td>
<td>Smart Factories</td>
<td>Consumer Electronics</td>
</tr>
<tr>
<td>Smartphones</td>
<td>Autonomous Vehicles</td>
<td>5G communications</td>
<td>Automotive</td>
<td>Smart Offices</td>
<td>Wearable Devices</td>
</tr>
<tr>
<td>5G Base Stations</td>
<td>Large Screen Display</td>
<td>Entertainment Platforms</td>
<td>Power Module</td>
<td></td>
<td>Gaming Consoles</td>
</tr>
<tr>
<td>Micro Cells</td>
<td>Smartwatches</td>
<td>LIDAR Sensors</td>
<td>Wireless Charging</td>
<td>HPC</td>
<td>Fitness Bands</td>
</tr>
<tr>
<td>Datacentres</td>
<td>Security</td>
<td>5G communications</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>HPC</td>
<td></td>
<td>Entertainment Platforms</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Internet of Things</td>
<td></td>
<td>LIDAR Sensors</td>
<td>Electric Vehicles</td>
<td>Smart Factories</td>
<td>Consumer Electronics</td>
</tr>
</tbody>
</table>

Optoelectronics

- Automotive
- Power Management & Energy
- Industrial
- Consumer

Mobility, Comm. and IT

- Personal Computers
- Smartphones
- 5G Base Stations
- Micro Cells
- Datacentres
- HPC
- Internet of Things

Optoelectronics

- Virtual Reality
- Autonomous Vehicles
- Large Screen Display
- Smartwatches
- Security

End-Market Applications
Wide Diversity of Semiconductor Usage

- LIDAR Sensors
- 5G communications
- Entertainment Platforms

- Electric Vehicles
- Automotive
- Power Module
- Wireless Charging

- Smart Factories
- Smart Offices

- Consumer Electronics
- Wearable Devices
- Gaming Consoles
- Fitness Bands

ASM Pacific Technology
Q3 2020
Financial and Operational Highlights
# Q3 2020 Group and Segment Revenue

<table>
<thead>
<tr>
<th></th>
<th>USD</th>
<th>YoY*</th>
<th>QoQ*</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Group</strong></td>
<td>551m</td>
<td>+2.6%</td>
<td>-1.2%</td>
</tr>
<tr>
<td><strong>Semi Solutions Segment</strong></td>
<td>247m</td>
<td>+5.0%</td>
<td>-11.5%</td>
</tr>
<tr>
<td><strong>Materials Segment</strong></td>
<td>78m</td>
<td>+22.4%</td>
<td>+4.8%</td>
</tr>
<tr>
<td><strong>SMT Solutions Segment</strong></td>
<td>226m</td>
<td>-5.1%</td>
<td>+10.6%</td>
</tr>
</tbody>
</table>

**Q3 2020 HIGHLIGHTS**

- **Group**
  - Group Revenue close to top end of guidance

- **SEMI**
  - IC/Discrete
    - Broad based demand
    - Mobile and Personal Computing Devices, HPC applications, 5G Infrastructure
  - Advanced Packaging
    - AP Revenue 9M 2020 same level as FY19 AP Revenue
  - OPTO
    - General lighting and conventional display applications
    - Mini LED customers started High Volume Manufacturing using our tools
  - China localization

- **Materials**
  - Q3 Revenue at record high at US$77.8M

- **SMT**
  - Driven by SiP applications for 5G-related devices, smartphones and wearables

*Period to period variances calculated using HKD*
No single customer accounted for more than 10% of Group revenue.

Top 5 customers only accounted for 15.53% of Group’s 9M 2020 revenue.

Top 20 customers include:
- World’s leading Telecommunication and Information Technology provider
- Leading High-Density Substrate makers
- World’s leading IDMs
- Tier 1 OSATs, major OSATs in China
- Major camera module makers
- Top EMS providers
- Leading automotive component suppliers

Among Top 20 customers of Group:
- 3 from SMT Solutions segment
- 7 from both Semi Solutions & SMT Solutions segment

9M 2020 Revenue Breakdown by Geography:
- China, 51.1%
- Europe, 11.6%
- Taiwan, 8.6%
- Americas, 7.9%
- Malaysia, 4.8%
- Korea, 4.3%
- Philippines, 1.6%
- Japan, 3.9%
- Vietnam, 1.2%
- India, 0.3%
- Others, 1.4%
- Thailand, 3.3%
- Others, 1.4%
### Q3 2020 Group and Segment Bookings

<table>
<thead>
<tr>
<th></th>
<th>USD</th>
<th>YoY*</th>
<th>QoQ*</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Group</strong></td>
<td>583m</td>
<td>+12.4%</td>
<td>+23.5%</td>
</tr>
<tr>
<td><strong>Semi Solutions Segment</strong></td>
<td>288m</td>
<td>+8.6%</td>
<td>+26.8%</td>
</tr>
<tr>
<td><strong>Materials Segment</strong></td>
<td>66m</td>
<td>+3.6%</td>
<td>-15.2%</td>
</tr>
<tr>
<td><strong>SMT Solutions Segment</strong></td>
<td>229m</td>
<td>+20.7%</td>
<td>+37.3%</td>
</tr>
</tbody>
</table>

**Group**
- 2nd highest Q3 Bookings; bucking historical trend of QoQ decline from Q2

**SEMI**
- IC/Discrete
  - Broad based demand
  - Mobile and Personal Computing Devices, HPC applications, 5G Infrastructure
- OPTO
  - General lighting and conventional displays
- CIS
  - Strong QoQ bookings growth in Q3 (relative to lower base in Q2)

**SMT**
- Driven by SiP applications for 5G-related devices, smartphones and wearables.
- Some signs of improvement for Automotive and Industrial

*Period to period variances calculated using HKD*
## Q3 2020 and 9M 2020 Group GM & Profitability

### Group Revenue (USD)
- **Q3 2020**: 551m +2.6% -1.2%
- **9M 2020**: 1.54b +4.7%

### Operating Profit (HKD)
- **Q3 2020**: 354m +1.5% -28.5%
- **9M 2020**: 996m +18.3%

### Net Profit (HKD)
- **Q3 2020**: 234m +5.2% -36.0%
- **9M 2020**: 625m +56.0%

### Gross Margin

<table>
<thead>
<tr>
<th>Segment</th>
<th>Q3 2020</th>
<th>9M 2020</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Gross Margin</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Group</td>
<td>32.9%</td>
<td>33.9%</td>
</tr>
<tr>
<td>Semi Solutions Segment</td>
<td>40.0%</td>
<td>41.4%</td>
</tr>
<tr>
<td>Materials Segment</td>
<td>19.4%</td>
<td>15.7%</td>
</tr>
<tr>
<td>SMT Solutions Segment</td>
<td>29.9%</td>
<td>31.1%</td>
</tr>
</tbody>
</table>

### SEMI
- Q3 GM declined primarily due to product mix, in particular weakness in CIS product market.

### Materials
- Q3 GM improvement anchored by higher volume effects
- Q3 Gross and Segment profits at record highs

### SMT
- Q3 GM declined largely due to lower revenue contribution from Automotive and Industrial, and geographical customer mix.

---

**Q 3 2020 HIGHLIGHTS**

**Group**
- 9M GM ▼ slightly YoY
  - Lower margins from SMT
- 9M Net Profit ▲ 56% YoY
  - Higher revenue
  - Lower expense (tight cost control & government grants)
- Q3 GM declined mainly due to lower margins from SEMI and SMT business

**SEMI**
- Q3 GM declined primarily due to product mix, in particular weakness in CIS product market.

**Materials**
- Q3 GM improvement anchored by higher volume effects
- Q3 Gross and Segment profits at record highs

**SMT**
- Q3 GM declined largely due to lower revenue contribution from Automotive and Industrial, and geographical customer mix.

*Period to period variances calculated using HKD*
R&D Commitment Makes Us a Preferred Partner of Choice

USD1,796 million invested in R&D

9M 2020 R&D expenditure

- US$ 155 million
- 11.6% of Equipment Sales

Q3 2020 HIGHLIGHTS
Business Segments Revenue Trend

**YoY* Growth:**

**Semiconductor Solutions (USD’M)**
- +5.0%

**Materials (USD’M)**
- +22.4%

**SMT Solutions (USD’M)**
- -5.1%

*Period to period variances calculated using HKD*
Business Segments Bookings Trend

**YoY* Growth:**

- **Semiconductor Solutions (USD'M)**: +8.6%
- **Materials (USD'M)**: +3.6%
- **SMT Solutions (USD'M)**: +20.7%

*Period to period variances calculated using HKD*
Growth Drivers
# Market Growth Driver – 5G Infrastructure

## Multi-Country, Multi-Year Driver from 5G Rollout

<table>
<thead>
<tr>
<th>Central Facility</th>
<th>Macro Tower Base Station</th>
<th>Clustered Micro Antennas</th>
</tr>
</thead>
<tbody>
<tr>
<td>(Houses routers, servers &amp; software that controls networks)</td>
<td>(Handles calls and data at slower speeds and greater distances)</td>
<td>Massive MIMO, (Short distances → Faster Speeds)</td>
</tr>
</tbody>
</table>

## Drivers for Capacity Buys

<table>
<thead>
<tr>
<th></th>
<th>4G Base Station</th>
<th>5G Base Station</th>
<th>Increase</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power Amplifiers</td>
<td>12 per Cell</td>
<td>96 to 192 per Cell</td>
<td>8x to 16x</td>
</tr>
</tbody>
</table>

## Drivers for Technology Buys

- System in Package
- Advanced Packaging

Source: Semiconductor Engineering
## Market Growth Driver – 5G Smartphones

Greater Demand for Higher Performance End Devices

<table>
<thead>
<tr>
<th></th>
<th>4G</th>
<th>5G</th>
<th>Increase</th>
</tr>
</thead>
<tbody>
<tr>
<td>Filters</td>
<td>40</td>
<td>70</td>
<td>1.75x</td>
</tr>
<tr>
<td>Bands</td>
<td>15</td>
<td>30</td>
<td>2.0x</td>
</tr>
<tr>
<td>Tx/Rx Filters</td>
<td>30</td>
<td>75</td>
<td>2.5x</td>
</tr>
<tr>
<td>Switch Throws</td>
<td>10</td>
<td>30</td>
<td>3.0x</td>
</tr>
<tr>
<td>CA Combos</td>
<td>10</td>
<td>200</td>
<td>20.0x</td>
</tr>
<tr>
<td>Sensors</td>
<td>6</td>
<td>7</td>
<td>1.17x</td>
</tr>
<tr>
<td>Camera Module</td>
<td>5</td>
<td>7</td>
<td>1.4x</td>
</tr>
<tr>
<td>Microphone</td>
<td>2</td>
<td>3</td>
<td>1.5x</td>
</tr>
</tbody>
</table>

- **System in Package**
- **Advanced Packaging**

Source: Skyworks Presentation, Huawei P30 Pro, P40 Pro+, iPhone product spec, management estimates
ASMPT Growth Enablers
Well Positioned to Capture Growth

Advanced Packaging Solutions (AP)
Comprehensive suite of AP Solutions

Light Emitting Diode Solutions (LED)
Key engagement with major mini and micro LED customers

Silicon Photonics Solutions
Sub-micron placement accuracy bonding capabilities

CMOS Image Sensor Solutions (CIS)
Winning automatic in-line solutions capabilities
Market Enabler – Advanced Packaging

The Growing Advanced Packaging Market Fuelled by Need to Enhance System Performance, Reduce Design Costs and Shorten Time to Market

Design costs continue to increase with greater demand for improved device functionality and performance

Increasing AP trend: Adoption of AP technologies in design and manufacturing will reduce cost and time to market

Packaging Revenue (USD)

Microprocessor performance (FLOPS)

Transistor (k)

Single thread performance

Frequency (MHz)

Typical power (W)

Number of cores

Source: Yole Development 2020
ASMPT Advanced Packaging Solutions

Comprehensive Suite of Solutions
Poised to Benefit From Accelerated Growth in AP

Markets Enabled By ASMPT’s Advanced Packaging Solutions

Now

Electric Vehicles
Wearables
5G Infrastructure
Data Centres

Emerging

High Performance Computing
Connected Homes
Autonomous Vehicles
Telemedicine
Artificial Intelligence
Factory Robotics

AP Processes

Physical Vapor Deposition
Electro-Chemical Deposition - Wafer/Panel Lvl Plating
Laser Dicing
Wafer/Panel Lvl Molding
Wafer/Panel Lvl Fan Out
Ultra Precision Die Bonding (Silicon Photonics)
Mass Transfer (Mini/Micro LED)
Multi-Chip Module Bonding
Thermo Compression Bonding
Flip Chip
Wafer Level Fan In
SMT/SIP Placement
Hybrid Bonding

ASMPT Solutions

Conductor
Stratus Series
Laser 1205
ORCAS
NUCLEUS
NANO
AD300 Series
VECTOR
FIREBIRD
AD8312FC
SUNBIRD
SIPLACE TX Micro

Coming Soon in 2021

ASMP Advanced Packaging Solutions

Pacific Technology
Market Enabler - Mini and Micro LED

**Mini LED**
*Medium to Large RGB / BLU Display*

Market Size CAGR (2019 - 2025) 
~ 35%

Source: LEDInside, Sep 2019

<table>
<thead>
<tr>
<th>Company</th>
<th>Conference/Event</th>
</tr>
</thead>
<tbody>
<tr>
<td>TCL</td>
<td>TCL Conference - 2019</td>
</tr>
<tr>
<td>LEYARD</td>
<td>InfoComm - 2019</td>
</tr>
<tr>
<td>CEDAR ELECTRONICS</td>
<td>InfoComm - 2019</td>
</tr>
<tr>
<td>KONKA</td>
<td>KONKA Conference - 2019</td>
</tr>
</tbody>
</table>

**Micro LED**
*Small Gadget & Transparent Display*

Market Size CAGR (2019 - 2025) 
~ 131%

Source: LEDInside, Sep 2019

<table>
<thead>
<tr>
<th>Company</th>
<th>Conference/Event</th>
</tr>
</thead>
<tbody>
<tr>
<td>RitDisplay + PlayNitride</td>
<td>Touch Taiwan - 2019</td>
</tr>
<tr>
<td>TIANMA</td>
<td>SID - 2019</td>
</tr>
<tr>
<td>AUO</td>
<td>Touch Taiwan - 2019</td>
</tr>
<tr>
<td>Samsung</td>
<td>CES - 2019</td>
</tr>
</tbody>
</table>

Source: Photos of displays from various conferences
ASMPT Mini & Micro LED Solutions

**Processes**

<table>
<thead>
<tr>
<th>End Market Applications</th>
<th>Digital Display</th>
<th>Television</th>
<th>Automotive</th>
<th>AR/VR</th>
<th>Wearable</th>
<th>Mobile</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td><img src="#" alt="Checkmark" /></td>
<td><img src="#" alt="Checkmark" /></td>
<td><img src="#" alt="Checkmark" /></td>
<td><img src="#" alt="Checkmark" /></td>
<td><img src="#" alt="Checkmark" /></td>
<td><img src="#" alt="Checkmark" /></td>
</tr>
</tbody>
</table>

**Pitch Size**

- **Die Size**
  - Conventional: 1.0mm to 10mm
  - Mini LED: 0.3mm to 1.0mm
  - Micro LED: 0.2mm < 50µm

**Pitch Size**

- Mini LED: 75µm – 200µm
- Micro LED: 50µm – 100µm

**Ocean Line: Fully Automatic Production Line for Micro LED**

**Inline Linker: Fully Automatic Production line for Mini LED**
Market Enabler – Silicon Photonics

Enabling Faster Data Bandwidth and Speed Transmission

Data Centres

10X

Higher Data Transmission Speed

4X

Greater Bandwidth 100gbps ➤ 400gbps

SI PHOTONICS MARKET SIZE
(IN USD MILLIONS)

480

CAGR = 46%

2019

3,900

2025

Source: Yole Developpement Silicon Photonics Market and Technology Report, May 2020
# ASMPT Silicon Photonics Solutions

## Placement Accuracy and Die Size

<table>
<thead>
<tr>
<th>Processes</th>
<th>Photonics</th>
<th>Silicon Photonics</th>
</tr>
</thead>
<tbody>
<tr>
<td>Placement Accuracy</td>
<td>2 – 10µm</td>
<td>0.3 – 2.0 µm</td>
</tr>
<tr>
<td>Die Size</td>
<td>150µm – 2000µm</td>
<td>150µm – 3000µm</td>
</tr>
</tbody>
</table>

## End Market Applications

<table>
<thead>
<tr>
<th>Application</th>
<th>Photonics</th>
<th>Silicon Photonics</th>
</tr>
</thead>
<tbody>
<tr>
<td>Data Centre-Cloud</td>
<td>✔</td>
<td>✔</td>
</tr>
<tr>
<td>Telecom - 5G</td>
<td>✔</td>
<td>✔</td>
</tr>
<tr>
<td>3D Sensing</td>
<td>✔</td>
<td></td>
</tr>
<tr>
<td>LiDAR</td>
<td>✔</td>
<td>✔</td>
</tr>
</tbody>
</table>
Outlook

Q4 Group Revenue Guidance
- US$530m – US$590m

Longer Term Outlook
- Accelerating roll-out of 5G infrastructure unlocking massive possibilities for data generation:
  - Upgrade cycle for 5G devices (including Electric Vehicles / Autonomous Vehicles)
  - Ever increasing demand for High Performance Computing
  - Steady proliferation of AI and machine learning applications
- Increasingly complex, sophisticated requirements for display (LED) and camera sensor (CIS) technologies
- ASMPT is strongly positioned to further innovate and develop advanced solutions to leverage and support these megatrends
Appendix
Other Q3 2020
Financial Information
**Q3 2020 Group Bookings**

**YoY* Growth:**  
+12.4%

<table>
<thead>
<tr>
<th></th>
<th>Q3 2020 Bookings</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>USD</td>
</tr>
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<tr>
<td>Materials Segment</td>
<td>66m</td>
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<tr>
<td>SMT Solutions Segment</td>
<td>229m</td>
</tr>
</tbody>
</table>

*Period to period variances calculated using HKD
## Q3 2020 Group Revenue

### YoY* Growth:

+2.6%

### Quarterly Group Revenue (USD’M)

<table>
<thead>
<tr>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
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<tbody>
<tr>
<td>Q1</td>
<td>250</td>
<td>280</td>
<td>300</td>
<td>330</td>
<td>350</td>
<td>380</td>
<td>400</td>
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<tr>
<td>Q2</td>
<td>360</td>
<td>390</td>
<td>420</td>
<td>450</td>
<td>480</td>
<td>510</td>
<td>540</td>
</tr>
<tr>
<td>Q3</td>
<td>440</td>
<td>470</td>
<td>500</td>
<td>530</td>
<td>560</td>
<td>590</td>
<td>620</td>
</tr>
<tr>
<td>Q4</td>
<td>520</td>
<td>550</td>
<td>580</td>
<td>610</td>
<td>640</td>
<td>670</td>
<td>700</td>
</tr>
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</table>

### Q3 2020 Revenue

<table>
<thead>
<tr>
<th></th>
<th>USD</th>
<th>YoY*</th>
<th>QoQ*</th>
</tr>
</thead>
<tbody>
<tr>
<td>Group</td>
<td>551m</td>
<td>+2.6%</td>
<td>-1.2%</td>
</tr>
<tr>
<td>Semi Solutions Segment</td>
<td>247m</td>
<td>+5.0%</td>
<td>-11.5%</td>
</tr>
<tr>
<td>Materials Segment</td>
<td>78m</td>
<td>+22.4%</td>
<td>+4.8%</td>
</tr>
<tr>
<td>SMT Solutions Segment</td>
<td>226m</td>
<td>-5.1%</td>
<td>+10.6%</td>
</tr>
</tbody>
</table>

*Period to period variances calculated using HKD 33
# Q3 2020 Group Financial Highlights

<table>
<thead>
<tr>
<th></th>
<th>Q3 2020</th>
<th>YoY*</th>
<th>QoQ*</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bookings (USD)</td>
<td>583m</td>
<td>+12.4%</td>
<td>+23.5%</td>
</tr>
<tr>
<td>Revenue (USD)</td>
<td>551m</td>
<td>+2.6%</td>
<td>-1.2%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>32.9%</td>
<td>-182 bps</td>
<td>-228 bps</td>
</tr>
<tr>
<td>EBIT (HKD)</td>
<td>347m</td>
<td>-8.7%</td>
<td>-24.0%</td>
</tr>
<tr>
<td>Net Profit (HKD)</td>
<td>234m</td>
<td>+5.2%</td>
<td>-36.0%</td>
</tr>
<tr>
<td>Net Profit Margin</td>
<td>5.5%</td>
<td>+14 bps</td>
<td>-298 bps</td>
</tr>
</tbody>
</table>

*Period to period variances calculated using HKD*
# Q3 2020 Segment Results – Semiconductor Solutions

<table>
<thead>
<tr>
<th></th>
<th>Q3 2020</th>
<th>YoY*</th>
<th>QoQ*</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bookings (USD)</td>
<td>288m</td>
<td>+8.6%</td>
<td>+26.8%</td>
</tr>
<tr>
<td>Revenue (USD)</td>
<td>247m</td>
<td>+5.0%</td>
<td>-11.5%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>40.0%</td>
<td>-348 bps</td>
<td>-293 bps</td>
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<tr>
<td>Segment Profit (HKD)</td>
<td>178m</td>
<td>-0.6%</td>
<td>-47.0%</td>
</tr>
<tr>
<td>Segment Profit Margin</td>
<td>9.3%</td>
<td>-52 bps</td>
<td>-622 bps</td>
</tr>
</tbody>
</table>

*Period to period variances calculated using HKD*
# Q3 2020 Segment Results – Materials

<table>
<thead>
<tr>
<th></th>
<th>Q3 2020</th>
<th>YoY*</th>
<th>QoQ*</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Bookings (USD)</td>
<td>66m</td>
<td>+3.6%</td>
<td>-15.2%</td>
</tr>
<tr>
<td>Revenue (USD)</td>
<td>78m</td>
<td>+22.4%</td>
<td>+4.8%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>19.4%</td>
<td>+907 bps</td>
<td>+250 bps</td>
</tr>
<tr>
<td>Segment Profit (HKD)</td>
<td>83m</td>
<td>+355.7%</td>
<td>+43.2%</td>
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<tr>
<td>Segment Profit Margin</td>
<td>13.8%</td>
<td>+1,010 bps</td>
<td>+370 bps</td>
</tr>
</tbody>
</table>

*Period to period variances calculated using HKD
### Q3 2020 Segment Results – SMT Solutions

<table>
<thead>
<tr>
<th></th>
<th>Q3 2020</th>
<th>YoY*</th>
<th>QoQ*</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bookings (USD)</td>
<td>229m</td>
<td>+20.7%</td>
<td>+37.3%</td>
</tr>
<tr>
<td>Revenue (USD)</td>
<td>226m</td>
<td>-5.1%</td>
<td>+10.6%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>29.9%</td>
<td>-277 bps</td>
<td>-147 bps</td>
</tr>
<tr>
<td>Segment Profit (HKD)</td>
<td>172m</td>
<td>-24.1%</td>
<td>+8.3%</td>
</tr>
<tr>
<td>Segment Profit Margin</td>
<td>9.8%</td>
<td>-247 bps</td>
<td>-21 bps</td>
</tr>
</tbody>
</table>

*Period to period variances calculated using HKD*
Thank You
Q&A